SUA-110H46-xx-S277

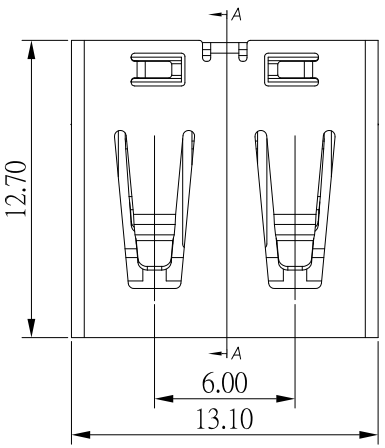
鍍層厚度 :

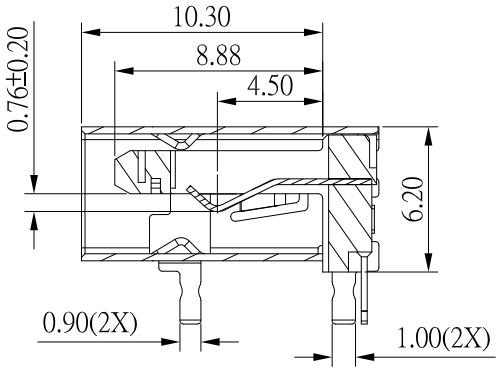
Blank : 1u"
2 : 15u"
3 : 30u"

Color :

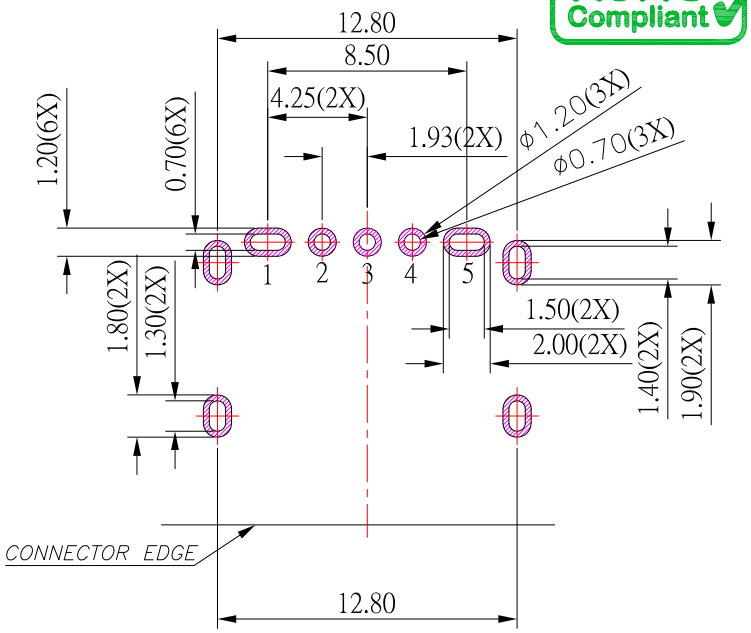
Black : B
Green : GR

RoHS Compliant

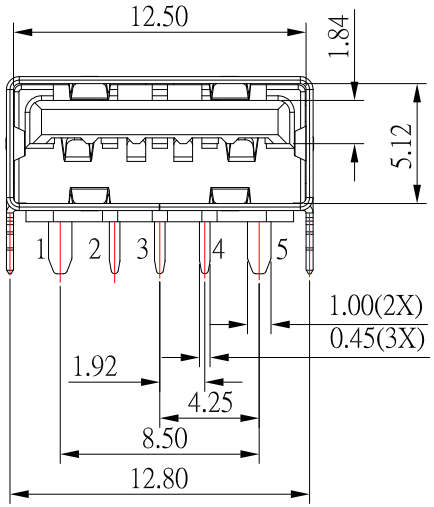


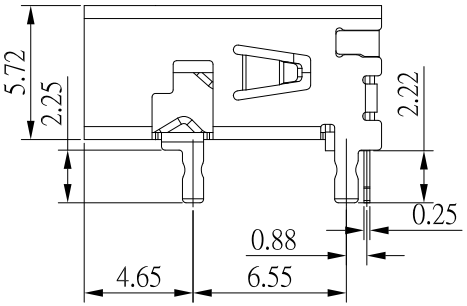


SECTION:A—A



RECOMMENDED PCB LAYOUT





NOTE:

1.MATERIAL:
- 1.1 Housing: PA10T
- 1.2 Contact: Copper Alloy
- 1.3 Shell: SUS

2.Finish:
- 2.1 Contact: Plated Gold in Mating Area ;
  Tin Plated on Solder Balls ;
  Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:
- 3.1 Current Rate: 5.0 A(VBUS & GND)
- 3.2 insulator Resistance:100MΩ Min
- 3.3 Dielectric Strength: 100V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Operation Temperature: -25℃ ~ +85℃
- 3.6 Insertion Force: 3.57 kgf Max
- 3.7 Extraction Force: 1.02 kgf Min

ITEM NO.	DESCRIPTION	DRAWN	DATE
4	更新圖面	Jack	052620
3	更新為A0版	Jack	101817
2	新增顏色編碼	Jack	100317
1	新增pin編號及圖示	Jack	092217

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED : Up to 5 ±0.2; Above 5 ~ 15 ±0.3; Above 15 ~ 30 ±0.4; Above 30 ~ 50 ±0.5; Angle ±0.3°

3RD. ANGEL'S | UNITS MM

		DATE
DRAWN BY:	Jack Lu	05/26/20
CHECKED BY:	Jacky Chen	05/26/20
APPROVED BY:	Tony Kao	05/26/20

MAT'L		TITLE	CONNECTOR
FINISH		MODLE	USB AF 2.0 90度 DIP 5PIN 直腳 無捲邊
SCALE	1 : 1	DWG NO.	SUA-110H46-xx-S277
SHEET NO.	1 of 1	PART NO.	SUA-110H46-xx-S277

SIZE A4 | VER R4